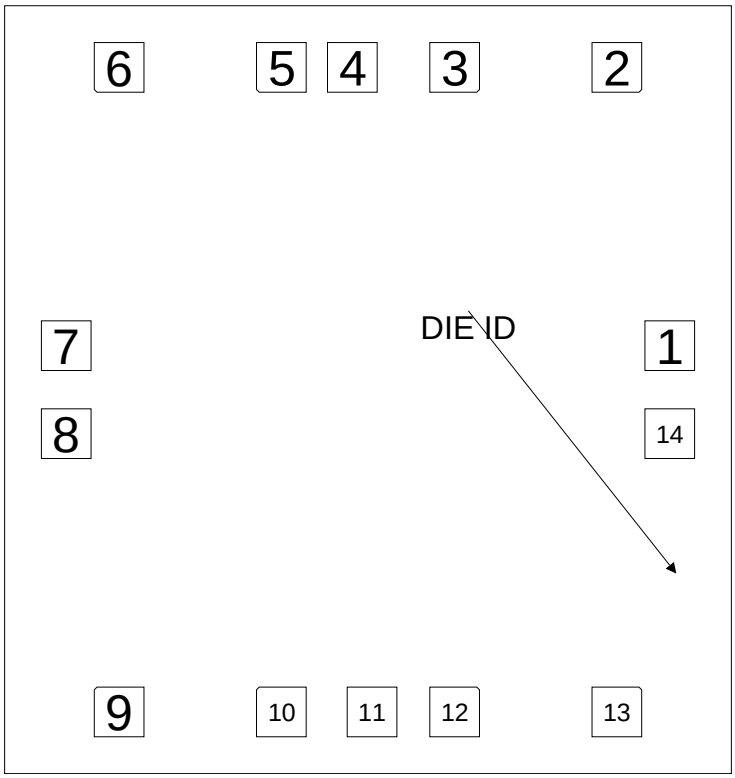
LM124 MDR MCD2920A
SMD#5962R9950401V9A
LOW POWER QUAD OPERATIONAL AMPLIFIER

AUG 17, 2010

DIE LAYOUT (H-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	1902H	Bond Pad Opening Size (min)	92.00µm x 92.00µm
Die Step	H	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	VOM ONLY
Wafer Diameter	150mm	Back Side Metal	BAREBACK
Die Size (Drawn)	1346.2µm x 1422.4µm 53.0mils x 56.0mils	Back Side Connection	Floating or GND
Thickness	330µm Nominal		
Min Pitch	127µm		
Note: All values are rounded to the nearest micron.			
Special Assembly Requirements:			

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Die Bond Pad Coordinate Locations(H-Step)
(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X		Y
Output 1	1	559	82	92	x	92
Input 1-	2	461	597	92	x	92
Input 1+	3	161	597	92	x	92
V+	4	-29	597	92	x	92
Input 2+	5	-161	597	92	x	92
Input 2-	6	-461	597	92	x	92
Output 2	7	-559	82	92	x	92
Output 3	8	-559	-82	92	x	92
Input 3-	9	-461	-597	92	x	92
Input 3+	10	-161	-597	92	x	92
Gnd	11	8	-597	92	x	92
Input 4+	12	161	-597	92	x	92
Input 4-	13	461	-597	92	x	92
Output 4	14	559	-82	92	x	92

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Notes

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